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Composition for cleaning post etch residues at an interconnect level for dual damascene system in integrated circuit manufacture comprises choline compound, water and organic solvent.

Patent Assignee: EKC TECHNOLOGY INC (EKCT-N)

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Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
WO 200002238	A1	20000113	WO 99US15157	A	19990702	200012 B
AU 9949690	A	20000124	AU 9949690	A	19990702	200027
EP 1127370	A1	20010829	EP 99933689	A	19990702	200150
			WO 99US15157	A	19990702	
TW 428241	A	20010401	TW 99111444	A	19990706	200156
KR 2001080865	A	20010825	KR 2001700187	A	20010106	200215
US 6417112	B1	20020709	US 9892024	A	19980706	200253
			US 99343532	A	19990630	
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			US 99343532	A	19990630	
			US 2000561744	A	20000428	
			US 20017134	A	20011204	

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Patent Details:

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Designated States (Regional): AT BE CH CY DE DK EA ES FI FR GB GH GM GR IE IT KE LS LU MC MW NL OA PT SD SE SL SZ UG ZW

AU 9949690 A H01L-021/02 Based on patent WO 200002238

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TW 428241 A H01L-021/30

KR 2001080865 A H01L-021/304

US 6417112 B1 H01L-021/302 Provisional application US 9892024

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Div ex application US 99343532

Div ex application US 2000561744

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